Design of Two-Stage Class AB CMOS Buffers: A Systematic Approach

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A systematic approach for the design of two-stage class AB CMOS unity-gain buffers is proposed. It is based on the inclusion of a class AB operation to class A Miller amplifier topologies in unity-gain negative feedback by a simple technique that does not modify quiescent currents, supply requirements, noise performance, or static power. Three design examples are fabricated in a 0.5 \(\mu\text{m}\) CMOS process. Measurement results show slew rate improvement factors of approximately 100 for the class AB buffers versus their class A counterparts for the same quiescent power consumption (< 200 \(\mu\text{W}\)).

Keywords: Analog integrated circuits, CMOS buffer, CMOS voltage follower, quasi-floating gate.

I. Introduction

Class AB buffers are required in low-power analog design and mixed-signal design to drive low impedance loads. In these scenarios, adequate dynamic performance must be compatible with low quiescent power consumption. This requirement is not viable if buffers operate in class A since, in this case, the load current is limited by the quiescent current of the output stage, leading to a tradeoff between slew rate and quiescent power. Class AB implementations solve this design constraint by providing dynamic currents to the load which are not limited by the quiescent currents. Several class AB buffers have been proposed which are mainly based on using a properly biased push-pull output stage [1]-[5]. However, typical shortcomings of these proposals are that the additional circuitry employed to get class AB operation often increases power consumption, decreases current efficiency (defined as the percentage of supply current that is delivered to the load), and sometimes does not feature accurate control of quiescent currents. Another typical shortcoming of some buffers is that there is a DC level shift between the input and the output voltage [6], [7], which is often dependent on temperature and process variations and that can be important if the buffer is used in a single-ended configuration.

In this paper, we propose a technique to systematically derive two-stage class AB unity-gain buffers from class A implementations. The technique is based on the use of quasi-floating gate (QFG) techniques [8]-[11] which allow the inclusion of a class AB operation without requiring additional power consumption or supply voltage and featuring a simple and accurate control of quiescent currents.

The paper is organized as follows. Section II describes the
systematic approach proposed and three design examples. Measurement results for a test chip prototype containing the three buffers and their class A versions are presented in section III. Finally, conclusions are drawn in section IV.

II. Systematic Design of Two-Stage Class AB Buffers

Figure 1 illustrates the basic design principle proposed. A generic class A buffer formed by a two-stage Miller amplifier in unity-gain negative feedback and shown in Fig. 1(a) is transformed into the class AB version of Fig. 1(b) by properly including a floating capacitor and a large resistive device, that is, making the gate of M2 a quasi-floating gate node. Details about the starting and resulting topologies are provided in the next paragraphs.

1. Class A Two-Stage Unity-Gain Buffer

Figure 1(a) shows a conventional two-stage class A unity-gain buffer. Amplifier A represents a generic single-stage amplifier with DC gain $A = G_{mA} R_A$, where $G_{mA}$ and $R_A$ are the transconductance and output resistance of the amplifier. The negative feedback loop formed by the amplifier and transistor $M_1$ has a high DC loop gain of $A_{ol} = G_{mA} R_A g_{m1} (r_{o1} || r_{o2})$, where $g_{m1}$ and $r_{o1}$ are the transconductance and output resistance of transistor $M_1$, respectively. This high loop gain forces the output voltage to track the input voltage, being the DC closed-loop gain of the buffer:

$$A_{cl} = \frac{V_{out}}{V_{in}} = \frac{A_{ol}}{1 + A_{ol}} \approx 1.$$  (1)

Also, due to the action of the feedback loop, the output resistance is very low. It is given by

$$R_{out} = \frac{1}{G_{mA} R_A g_{m1}}.$$  (2)

Stability of the feedback loop in Fig. 1(a) is enforced by creating a dominant pole $f_{p1}$ at node X using Miller compensation by capacitor $C_C$. A nulling resistor is often employed, as show in Fig. 1(a). The non-dominant pole $f_{p2}$ corresponds to the output node. These poles are:

$$f_{p1} \approx \frac{1}{2 \pi R_A g_{m1} (r_{o1} || r_{o2}) C_C},$$  (3)

$$f_{p2} \approx \frac{g_{m1}}{2 \pi (C_X + C_L)},$$  (4)

where $C_X = C_{GS1}$ is the intrinsic capacitance at node X, yielding a bandwidth for the buffer of approximately

$$f_{-3dB} = \frac{f_{p2}}{\sqrt{2}} \left( \frac{4 + \frac{GB}{f_{p2}}}{1 + \frac{GB}{f_{p2}}} \right)^{-1},$$  (4)

where $GB = A_{ol} f_{p1}$. Figure 2 illustrates in graphical form the dependence of the follower bandwidth on $f_{p2}$, both normalized by $GB$. Note that when $f_{p2} >> GB$, then $f_{-3dB} = GB$; otherwise, $f_{-3dB} = GB$, and $f_{-3dB}$ decreases as $f_{p2}$ decreases (for example, when the load capacitor $C_L$ increases).

Despite the high accuracy and low output resistance of the buffer of Fig. 1(a), the maximum current that the circuit can deliver to the load is limited by the quiescent current $I_B$ of the output stage, which limits positive slew rate to

$$SR_c = \frac{I_{max}}{C_L + C_C} = \frac{I_B}{C_L + C_C},$$  (5)

where $C_L$ is the load capacitor. Hence, a large slew rate requires large quiescent power consumption. Note that (5) assumes that amplifier A has enough driving capability in order not to additionally limit slewing.

2. Proposed Class AB Two-Stage Unity-Gain Buffer

To avoid this drawback, the class AB topology of Fig. 1(b) can be derived which results from including a capacitor $C_{bat}$ between nodes X and Y and a large resistive device $R_{large}$ between node Y and the biasing voltage $V_B$. This modification makes the gate of M2 a quasi-floating node [9] with well

![Fig. 1. (a) Class A voltage follower and (b) class AB QFG voltage follower.](image)

![Fig. 2. Graphical representation of (4).](image)
established DC voltage $V_B$ but floating from a signal viewpoint. The static behavior of the circuit of Fig. 1(b) is identical to that of Fig. 1(a) since capacitance $C_{bat}$ has no effect in quiescent conditions, and there is no voltage drop in resistance $R_{large}$. Hence, the quiescent current $I_{th}$ in the output branch is accurately controlled as it is the result of mirroring the current in $M_3$, just as for the circuit of Fig. 1(a). If necessary, the quiescent current could be made very small to save static power because it does not limit slew rate in the class AB circuit of Fig. 1(b). A description follows. Assume that the input voltage $V_a$ increases. For the output voltage to accurately track such variation as fast as possible, a large current must be delivered to the load. This large current can be delivered in Fig. 1(b) since an increase $\Delta V_a$ at the input leads to a decrease $-\Delta V_a$ at node $X$. Due to the large value of resistance $R_{large}$ capacitor $C_{bat}$ cannot discharge rapidly. Hence, this capacitor acts as a floating battery that translates this voltage decrease at node $X$ to node $Y$, thus increasing the $V_{CG}$ of $M_2$ and providing the required output current. The decrease of voltage at node $X$ also decreases the current in $M_1$ below $I_{th}$, which also contributes to increasing the output current. Likewise, when input voltage decreases voltages at nodes $X$ and $Y$ increases, thus decreasing current in $M_2$ and increasing current in $M_1$ and resulting in a large current sunk from the load.

More specifically, RC high-pass filtering takes place between node $X$ and node $Y$ which is given by

$$
\frac{V_Y(s)}{V_X(s)} = \frac{sR_{large}(C_{bat} + C_Y)}{sR_{large}(C_{bat} + C_Y) + 1},
$$

where $\alpha = C_{bat}/(C_{bat} + C_Y)$, and $C_Y$ is the parasitic capacitance at node $Y$. Note that $C_Y$ leads to attenuation $\alpha$ from $X$ to $Y$, which sets the minimum required value for $C_{bat}$. Capacitance $C_Y$ is dominated by $C_{GS1}$. It is important to connect the top plate of $C_{bat}$ to node $Y$ instead of the bottom plate to minimize $C_Y$. The large resistance $R_{large}$ does not need to have a precise value as long as it is high enough to provide a cutoff frequency $1/[2\pi R_{large}(C_{bat}+C_Y)]$ lower than the minimum frequency component in node $X$ to be transferred to node $Y$. Process, voltage, and temperature variations affecting the value of $R_{large}$ are not relevant, and it can be implemented by a minimum-size diode-connected MOS transistor in a cutoff region or minimum-size transistor biased by another identical transistor in subthreshold region [12], leading to a compact and power-efficient implementation. Simulated values of $R_{large}$ for this implementation range from 670 GΩ to 77 GΩ for a temperature interval from $-40^\circ\text{C}$ to $120^\circ\text{C}$. The corresponding cutoff frequency ranges from 0.23 Hz to 2 Hz.

The only difference between the buffers of Fig. 1(a) and Fig. 1(b) in terms of small-signal operation is that $M_1$ is just a biasing transistor in Fig. 1(a), but it contributes to the transconductance gain of the output stage in Fig. 1(b). Hence, the small-signal expressions for the class A buffer in subsection II.1 apply by replacing $g_{m1}$ by $g_{m1} + \alpha g_{m2}$. Thus, the low-frequency gain of the follower of Fig. 1(b) is given by (1), but here the loop gain increases to $A_{v} = g_{m1} R_s (g_{m1} + \alpha g_{m2}) |r_{o2}|/r_{o2}$.

The output resistance becomes

$$
R_{out} = \frac{1}{G_{m1} R_s (g_{m1} + \alpha g_{m2})}.
$$

The dominant pole $f_1$ and non-dominant pole $f_2$ become

$$
f_1 = \frac{1}{2\pi R_s (g_{m1} + \alpha g_{m2}) (r_{o1} || r_{o2}) C_C},
$$

$$
f_2 = \frac{g_{m1} + \alpha g_{m2}}{2\pi (C_X + C_Y)}
$$

where $C_X$ now increases to

$$
C_X = \frac{C_{GS1} + C_{Cb}}{C_{bat} + C_Y},
$$

with $C_{Cb}$ the bottom-plate to substrate capacitance of $C_{bat}$. Hence, the QFG technique increases the follower gain and decreases the output resistance and dominant pole frequency. Note, however, that the product $GB = A_{f1}$ is the same as the class A follower. For $C_Y > C_X$, the increase in $C_Y$ from (9) is not significant in (8) and the increase in the numerator of $f_2$ shifts $f_2$ to higher frequencies. From (4), this may slightly increase bandwidth of the class AB buffer versus its class A counterpart, as shown in Table 1. This increase is also observed in other QFG circuits [10].

Under quiescent conditions, current in $M_2$ is $I_2 = I_{th}$ and

$$
V_{SG2} = V_{Q} = \frac{2I_1}{\beta_2} + |V_{TH1}|,
$$

where $V_{TH1}$ and $\beta_2 = \mu C_{ox}(W/L)_{M2}$ are the threshold voltage and transconductance factor, respectively, of transistor $M_2$, and superscript $Q$ indicates quiescent value. When a positive input step $V_{step}$ is applied to the buffer, voltage at node $Y$ suddenly decreases by $-\alpha AV_{step}$, leading to a current in $M_2$ which becomes larger than $I_{th}$:

$$
I_2 = \frac{\beta_2}{2} \left( V_{SG2} + \alpha AV_{step} - |V_{TH1}| \right)^2
$$

$$
= \frac{\beta_2}{2} \left( \frac{2I_1}{\beta_2} + \alpha AV_{step} \right)^2.
$$

Note from (11) that current $I_2$ is not bounded by $I_{th}$, reflecting the class AB operation. For

$$
V_{step} > > \frac{1}{\alpha \sqrt{\frac{2I_1}{\beta_2}}},
$$

the output current is $I_{out} = I_2$ and $SR$, becomes approximately


\[
SR_\alpha \approx \frac{\beta_2}{2(C_L + C_C)} \left( \frac{2I_B}{\beta_2} + \alpha AV_{\text{step}} \right)^2, \tag{13}
\]

which leads to a \(SR\) increase over the class A topology:

\[
\frac{SR_{\alpha,\text{AB}}}{SR_{\alpha,A}} \approx \frac{I_{\text{MAX,AB}}}{I_{\text{MAX,A}}} \left( \frac{2I_B}{\beta_2} + \alpha AV_{\text{step}} \right)^2. \tag{14}
\]

In practice, slew rate may be limited to lower values. First, the output of amplifier A may saturate to a voltage \(V_{\text{sat}}\). If \(\alpha AV_{\text{step}} \geq |V_{G1}^O - V_{\text{sat}}|\), then \(|V_{G1}^O - V_{\text{sat}}|\) should replace \(\alpha AV_{\text{step}}\) in (13) and (14) reducing \(SR\). Second, slew rate limitation of amplifier A to drive the compensation capacitance \(C_C\) and the intrinsic capacitance \(C_Y\) may ultimately limit \(SR\).

The proposed buffer of Fig. 1(b) can be regarded as an extension of the simple topology reported in [13], replacing the input transistor by a generic input stage (amplifier A). A bulk-driven alternative realization of the follower in [13] is reported in [14].

Note that the principle of operation of the two-stage operational transconductance amplifier (OTA) used in Fig. 1(b) is similar to that of a conventional class-AB two-stage OTA. In this latter case, a class AB push-pull output stage is also used; however, it is based on creating a DC level shift between the gates of the output transistors by diode-connected transistors. This conventional implementation increases static power and supply voltage requirements and does not feature accurate control of quiescent currents, which are dependent on process and temperature variations.

3. Implementation of Amplifier A

A new family of class AB buffers can be obtained by using different implementations for amplifier A in Fig. 1(b), allowing design of such buffers in a systematic way. In this paper, we employ three possible realizations, shown in Fig. 3.

In the circuit of Fig. 3(a), gain is provided by \(M_6\). If just this transistor were used in the signal path, a DC level shift equal to the quiescent value of \(V_{\text{GOS}}\) would appear between the amplifier inputs. Such DC level shift depends on process and temperature variations, and also on the bulk effect if \(M_3\) is not embodied in a well tied to its source terminal. To compensate for this DC level shift, a matched diode-connected transistor \(M_4\) biased with the same current is included. Both \(M_4\) and \(M_3\) have been embodied in a common well tied to the common source terminal, thus avoiding the body effect (which was already strongly mitigated by the level shift cancellation scheme). The DC gain of the amplifier is \(A=\frac{g_{m5}}{r_{o5}}\).

A second implementation of amplifier A is shown in Fig. 3(b). It is an alternative biasing of the circuit of Fig. 3(a) aimed to tolerate a larger input common mode range. For this reason, cascode current sources are not employed. To preserve accuracy, transistor \(M_{12}\) (matched with \(M_3\) and \(M_4\)) is included. It provides the same \(V_{DS}\) voltage to transistors \(M_{13}\) and \(M_5\), so even when \(M_{13}\) and \(M_7\) enter triode region, the current across \(M_{13}\) and \(M_4\) will still be exactly half that of \(M_5\), thus yielding accurate voltage copy between the buffer input \(V_{in}\) and output \(V_{out}\). The DC gain is \(A=\frac{g_{m5}}{r_{o5}}\).

The third implementation in Fig. 3(c) is a conventional differential pair, providing a DC gain \(A=\frac{g_{m5}}{r_{o5}}\).

Note that the amplifiers in Fig. 3 do not have rail-to-rail common-mode input range; hence, the resulting buffer is not rail-to-rail. To solve this, the input transistors could be replaced by floating-gate MOS transistors as in [15]. Note also that the driving capability of these amplifiers is limited to \(2I_B\). If this value is not enough, then adaptive biasing could be used in the circuits of Fig. 3 as in [16], yielding a class AB amplifier.

III. Measurement Results

A total of six buffers were fabricated in a test chip prototype.
using a 0.5 μm CMOS n-well process with nominal nMOS and pMOS threshold voltages of 0.67 V and −0.96 V, respectively. A microphotograph of the chip is shown in Fig. 4. Three buffers operate in class A, and they correspond to the circuit of Fig. 1(a) by replacing amplifier A by the three circuits of Fig. 3. The other three buffers operate in class AB and correspond to the replacement of amplifier A in Fig. 1(b) by the three topologies of Fig. 3. Supply voltage was set to ±1.65 V, and the bias current was \( I_b = 10 \mu A \). Transistor dimensions in μm/μm are 60/1 (M1, M8, M9, M10, M11, M14), 100/0.6 (M2, M3, M6, M6c), 200/0.6 (M7, M7c), and 100/1 (M4, M5, M8c, M9c, M11c, M12). An off-chip load capacitor of 22 pF was employed, which added to the pad and board parasitics leads an estimated load capacitance of about 30 pF. Capacitor \( C_{bat} \) was of 1 pF, \( C_C = 2 \) pF, and \( R_{large} \) is a diode-connected PMOS of 1.5/0.6.

Figure 5 shows the measured harmonic distortion of the three fabricated class AB buffers following the approach of Fig. 1(b). Note that in all cases total harmonic distortion (THD) is below −60 dB for input amplitudes of 1 Vpp and below −50 dB for input amplitudes of 2 Vpp. Note also that distortion is dominated by the second-order harmonic. Therefore, a differential configuration would feature strongly reduced distortion levels dominated by the low third-order harmonic shown in the graphs of Fig. 5.

As expected, the lowest distortion for high input amplitudes corresponds to the buffer using the amplifier of Fig. 3(b), which is designed to tolerate the upper bias transistors to operate in triode region. For low to medium input amplitudes, the buffer using the amplifier of Fig. 3(c) provides the best linearity, with THD < −70 dB for \( V_{pp} \leq 1.5 \) Vpp. A comparison of the measured THD for the class A and class AB buffers of Fig. 1 is shown in Fig. 6. The upper graph compares the buffers using amplifier A of Fig. 3(a). The middle graph corresponds to the amplifier of Fig. 3(b). The lower one corresponds to that of Fig. 3(c). Note that although THD is similar for low input amplitudes, it strongly increases for the class A versions when input amplitude increases. This is due to slew-rate limitations of the class A buffers, which are unable to track the rate at which input voltage increases for this load capacitance, strongly distorting the output waveform.

Figure 7 shows the measured response of the class A and AB buffers of Fig. 1 when an input square waveform of 100 kHz and 1.8 Vpp is applied. The amplifier of Fig. 3(b) is used for both class A and class AB buffers. Note the increase in \( SR_+ \), which is 0.32 V/μs for the class A buffer and 29 V/μs for the class AB version. Similar results are obtained for the two other amplifiers of Fig. 3, which are not shown for brevity.

Table 1 summarizes the main performance parameters of the six fabricated buffers. Buffer class AB numbers 1, 2, or 3 correspond to the circuit of Fig. 1(b) with amplifier of Figs. 3(a) to (c), respectively. Similar notation is used for the class A buffers based on Fig. 1(a). Measurements in Table 1
show that the class AB buffers improve slew rate by an approximate factor of 100, improve bandwidth by around 20%, and they do not degrade quiescent power or noise performance compared with the class A versions, but require only a modest increase in silicon area.

Comparison with some other class AB followers previously reported is shown in Table 2. Dynamic performance is difficult to compare since different loads and supply currents are used in different papers. To overcome this issue, Table 2 shows the current efficiency of the output stage ($I_{\text{max}}/I_{\text{bias}}$), that is, the ratio between the maximum output current $I_{\text{max}} \approx \text{SR} \cdot C_L$ and the bias current $I_{\text{bias}}$ of the output branch. It can be observed that the three class AB topologies presented here show higher current efficiency driving the load than the other references in Table 2. Also in Table 2, the ratio between $I_{\text{max}}$ and the total quiescent current supplied $I_{\text{supply}}$ is shown. The proposed buffers also compare favorably in terms of this ratio as well as in linearity and silicon area (considering the differences in feature size).

High-performance class AB buffers can be made featuring the high accuracy and dynamic range from class AB three-stage amplifiers [5]. The focus in this work is on micropower buffers for which having less stages is beneficial. However, the technique proposed could be expanded to three-stage implementations by using the idea of Fig. 1(b) at the output stage.

Table 1. Measured performance of class A and class AB buffers.

<table>
<thead>
<tr>
<th>Buffer</th>
<th>SR+ (V/µs)</th>
<th>THD@1Vpp, 100 kHz (dB)</th>
<th>Input noise @50 kHz (nV/√Hz)</th>
<th>Quiescent power (µW)</th>
<th>BW (MHz)</th>
<th>Area (mm²)</th>
</tr>
</thead>
<tbody>
<tr>
<td>A#1</td>
<td>25</td>
<td>-63.8</td>
<td>42</td>
<td>198</td>
<td>12.2</td>
<td>0.014</td>
</tr>
<tr>
<td>A#2</td>
<td>29</td>
<td>-33.7</td>
<td>44</td>
<td>198</td>
<td>10.4</td>
<td>0.011</td>
</tr>
<tr>
<td>A#3</td>
<td>30</td>
<td>-74.3</td>
<td>55</td>
<td>198</td>
<td>13.4</td>
<td>0.017</td>
</tr>
<tr>
<td>AB#1</td>
<td>20</td>
<td>-41.3</td>
<td>57</td>
<td>198</td>
<td>11.9</td>
<td>0.015</td>
</tr>
<tr>
<td>AB#2</td>
<td>21</td>
<td>-71.5</td>
<td>30</td>
<td>198</td>
<td>8.4</td>
<td>0.025</td>
</tr>
<tr>
<td>AB#3</td>
<td>22</td>
<td>-24.2</td>
<td>30</td>
<td>165</td>
<td>5.8</td>
<td>0.021</td>
</tr>
</tbody>
</table>

Fig. 6. Comparison of measured THD at 100 kHz for class A and class AB buffers of Fig. 1, using different input amplitudes: (a) buffers using amplifier A of Fig. 3(a), (b) buffers using amplifier A of Fig. 3(b), and (c) buffers using amplifier A of Fig. 3(c).

Fig. 7. Measured transient response of buffers in Fig. 1 using amplifier A of Fig. 3(b): (a) input waveform and (b) output waveforms of class A and class AB buffers.

IV. Conclusion

A new and systematic way of designing class AB unity-gain buffers has been presented. The proposed method is based on using QFG transistors in the output stage of the general scheme.
Table 2. Measured performance comparison with other class AB buffers.

<table>
<thead>
<tr>
<th></th>
<th>This work AB #1</th>
<th>This work AB #2</th>
<th>This work AB #3</th>
<th>Wong [1]</th>
<th>Kenney [7]</th>
<th>Lu [17]</th>
<th>Torralba [18]</th>
<th>Xing [19]</th>
<th>Lu [20]</th>
</tr>
</thead>
<tbody>
<tr>
<td>CMOS tech.</td>
<td>0.5 μm</td>
<td>0.5 μm</td>
<td>0.5 μm</td>
<td>3 μm</td>
<td>2 μm</td>
<td>0.35 μm</td>
<td>0.5 μm</td>
<td>0.35 μm</td>
<td>0.35 μm</td>
</tr>
<tr>
<td>Supply volt.</td>
<td>±1.65 V</td>
<td>±1.65 V</td>
<td>±1.65 V</td>
<td>±2.5 V</td>
<td>5 V</td>
<td>3.3 V</td>
<td>3.3 V</td>
<td>3.3 V</td>
<td>3.3 V</td>
</tr>
<tr>
<td>Load capac.</td>
<td>30 pF</td>
<td>30 pF</td>
<td>30 pF</td>
<td>5 nF</td>
<td>20 pF</td>
<td>150 pF</td>
<td>18 pF</td>
<td>12 pF</td>
<td>150 pF</td>
</tr>
<tr>
<td>SR+</td>
<td>25 V/μs</td>
<td>29 V/μs</td>
<td>20 V/μs</td>
<td>0.9 V/μs</td>
<td>50 V/μs</td>
<td>2.7 V/μs</td>
<td>6.2 V/μs</td>
<td>200 V/μs</td>
<td>3.9 V/μs</td>
</tr>
<tr>
<td>SR−</td>
<td>−27 V/μs</td>
<td>−35 V/μs</td>
<td>−17 V/μs</td>
<td>−0.9 V/μs</td>
<td>NA</td>
<td>−3.8 V/μs</td>
<td>−14.5 V/μs</td>
<td>NA</td>
<td>−2.7 V/μs</td>
</tr>
<tr>
<td>$I_{max}/I_{sink}$</td>
<td>80</td>
<td>92.8</td>
<td>64</td>
<td>40</td>
<td>4.3</td>
<td>NA</td>
<td>3.7</td>
<td>4.8</td>
<td>NA</td>
</tr>
<tr>
<td>$V_{max}/I_{supply}$</td>
<td>13.3</td>
<td>15.4</td>
<td>10.7</td>
<td>15</td>
<td>3.8</td>
<td>1.8</td>
<td>1.9</td>
<td>2.4</td>
<td>2.7</td>
</tr>
<tr>
<td>THD</td>
<td>−63.8 dB</td>
<td>−74.3 dB</td>
<td>−71.5 dB</td>
<td>−48 dB</td>
<td>−60 dB</td>
<td>−62.8 dB</td>
<td>−50 dB</td>
<td>−48 dB</td>
<td>−64.5dB</td>
</tr>
<tr>
<td>(%1 Vpp, 100 kHz)</td>
<td>(0.1 Vpp, 100 kHz)</td>
<td>(0.3 Vpp, 100 kHz)</td>
<td>(0.4 Vpp, 100 kHz)</td>
<td>(0.1 Vpp, 100 kHz)</td>
<td>(0.2 Vpp, 100 kHz)</td>
<td>(0.6 Vpp, 1 MHz)</td>
<td>(0.08 Vpp, 700 kHz)</td>
<td>(1 Vpp, 20 kHz)</td>
<td></td>
</tr>
<tr>
<td>PSRR</td>
<td>56 dB</td>
<td>51 dB</td>
<td>53 dB</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>&gt;60 dB</td>
<td>NA</td>
</tr>
<tr>
<td>Input noise</td>
<td>8 mV</td>
<td>10 mV</td>
<td>5 mV</td>
<td>&lt;10 mV</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>8.8 mV</td>
</tr>
<tr>
<td>@50 kHz</td>
<td>42 nV/√Hz</td>
<td>55 nV/√Hz</td>
<td>30 nV/√Hz</td>
<td>70 nV/√Hz</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
</tr>
<tr>
<td>Quiescent power</td>
<td>198 μW</td>
<td>198 μW</td>
<td>165 μW</td>
<td>1.5 mW</td>
<td>1.3 mW</td>
<td>660 μW</td>
<td>90 μW</td>
<td>3.3 mW</td>
<td>714 μW</td>
</tr>
<tr>
<td>Bandwidth</td>
<td>12.2 MHz</td>
<td>13.4 MHz</td>
<td>8.4 MHz</td>
<td>6 MHz</td>
<td>6 MHz</td>
<td>NA</td>
<td>87 MHz</td>
<td>NA</td>
<td>NA</td>
</tr>
<tr>
<td>Silicon area</td>
<td>0.014 mm²</td>
<td>0.017 mm²</td>
<td>0.025 mm²</td>
<td>0.645 mm²</td>
<td>NA</td>
<td>0.012 mm²</td>
<td>0.010 mm²</td>
<td>0.087 mm²</td>
<td></td>
</tr>
</tbody>
</table>

of Fig. 1(a). Measurements demonstrate a notable improvement of dynamic performance with a minor penalty in terms of silicon area. The slew rate improvement factor is requiring accurate operation with very low quiescent power consumption.

References


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